

FAST CMOS BUFFER/CLOCK DRIVER

IDT49FCT805/A

FEATURES:

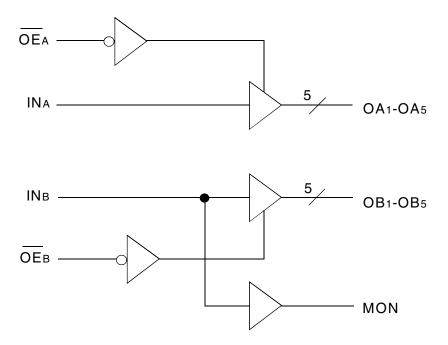
- 0.5 MICRON CMOS Technology
- Guaranteed low skew < 700ps (max.)
- · Low duty cycle distortion < 1ns (max.)
- · Low CMOS power levels
- TTL compatible inputs and outputs
- · Rail-to-rail output voltage swing
- High drive: -24mA Іон, +64mA Іоь
- · Two independent output banks with 3-state control
- 1:5 fanout per bank
- "Heartbeat" monitor output
- · Available in SSOP and SOIC packages

DESCRIPTION:

The 49FCT805 is a non-inverting buffer/clock driver built using advanced dual metal CMOS technology. Each bank consists of two banks of drivers. Each bank drives five output buffers from a standard TTL compatible input. These devices feature a "heart-beat" monitor for diagnostics and PLL driving. The MON output is identical to all other outputs and complies with the output specifications in this document.

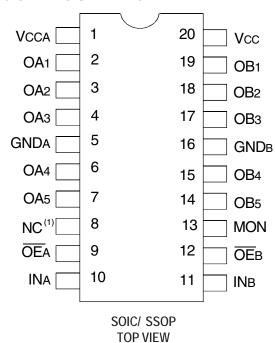
The 49FCT805 offers low capacitance inputs and hysteresis. Rail-to-rail output swing improves noise margin and allows easy interface with CMOS inputs.

FUNCTIONAL BLOCK DIAGRAM



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PIN CONFIGURATION



NOTE:

1. Pin 8 is not internally connected on devices with a "K" prefix in the date code. On older devices, pin 8 is internally connected to GND. To insure compatibility with all products, pin 8 should be connected to GND at the board level.

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
Tstg	Storage Temperature	-65 to +150	°C
lout	DC Output Current	-60 to +60	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
 permanent damage to the device. This is a stress rating only and functional operation
 of the device at these or any other conditions above those indicated in the operational
 sections of this specification is not implied. Exposure to absolute maximum rating
 conditions for extended periods may affect reliability.
- 2. Input and Vcc terminals.
- 3. Output and I/O terminals.

CAPACITANCE (TA = $+25^{\circ}$ C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	4.5	6	pF
Соит	Output Capacitance	Vout = 0V	5.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
OEA, OEB	3-State Output Enable Inputs (Active LOW)
INA, INB	Clock Inputs
OAn, OBn	Clock Outputs
MON	Monitor Output

FUNCTION TABLE (1)

Inp	uts	Outputs		
OEA, OEB	INA, INB	OAn, OBn	MON	
L	L	L	L	
L	Н	Н	Н	
Н	L	Z	L	
Н	Н	Z	Н	

NOTE:

1. H = HIGH

L = LOW

Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: $V_{LC} = 0.2V$; $V_{HC} = V_{CC} - 0.2V$ Commercial: $T_A = 0^{\circ}C$ to $+70^{\circ}C$, Industrial: $T_A = -40^{\circ}C$ to $+85^{\circ}C$, $V_{CC} = 5V \pm 5\%$

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
Vih	Input HIGH Level (Input pins)	Guaranteed Logic HIGH Level		2	_	_	V
VIL	Input LOW Level (Input and I/O pins)	Guaranteed Logic LOW Level		T -	_	0.8	V
lін	Input HIGH Current	Vcc = Max.	VI = 5.5V	<u> </u>	_	±1	μΑ
lıL	Input LOW Current	Vcc = Max.	VI = GND	_	_	±1	μΑ
lozh	Off State (Hi-Z) Output Current	Vcc = Max.	Vo = Vcc	_	_	±1	μΑ
lozl			Vo = GND	_	_	±1	
Vik	Clamp Diode Voltage	VCC = Min., IIN = -18mA		_	-0.7	-1.2	V
los	Short Circuit Current	Vcc = Max., Vo = GND ⁽³⁾		-60	-120	_	mA
		VCC = 3V, VIN = VLC or VHC	IOH = -32μA	VHC	Vcc	_	
Vон	Output HIGH Voltage	Vcc = Min.	Іон = -300μА	VHC	Vcc	_	V
		VIN = VIH or VIL	Iон = -15mA	3.6	4.3	_	
			Iон = -24mA	2.4	3.8	_	
		VCC = 3V, VIN = VLC or VHC	IoL = 300μA	T -	GND	VLC	
Vol	Output LOW Voltage	Vcc = Min.	IoL = 300mA	-	GND	VLC	V
		VIN = VIH or VIL	IoL = 64mA	<u> </u>	0.3	0.55	1
VH	Input Hysteresis for all inputs	<u> </u>		T -	200	_	mV
Icc	Quiescent Power Supply Current	Vcc = Max., Vin = GND or Vcc		_	5	500	μΑ

NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5V, +25°C ambient.
- 3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
Δlcc	Quiescent Power Supply Current	Vcc = Max.		_	1	2.5	mA
	TTL Inputs HIGH	$VIN = 3.4V^{(3)}$					
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max.	VIN = VCC	_	0.15	0.2	mA/MHz
		Outputs Open	VIN = GND				
		OEA = OEB = GND					
		50% Duty Cycle					
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max.	VIN = VCC	_	1.5	2.5	
		Outputs Open	VIN = GND				
		fo = 10MHz					
		50% Duty Cycle	VIN = 3.4V	_	2	3.8	
		OEA = OEB = VCC	VIN = GND				
		Mon. Output Toggling					
		Vcc = Max.	VIN = VCC	_	4.1	6 ⁽⁵⁾	mA
		Outputs Open	VIN = GND				
		fo = 2.5MHz					
		50% Duty Cycle	VIN = 3.4V	_	5.1	8.5 ⁽⁵⁾	
		OEA = OEB = GND	VIN = GND				
		Eleven Outputs Toggling					

NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V); all other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- 5. Values for these conditions are examples of the Ic formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - $IC = ICC + \Delta ICC DHNT + ICCD (foNo)$
 - Icc = Quiescent Current (IccL, IccH and Iccz)
 - Δ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V)
 - DH = Duty Cycle for TTL Inputs High
 - NT = Number of TTL Inputs at DH
 - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 - fo = Output Frequency
 - No = Number of Outputs at fo
 - All currents are in milliamps and all frequencies are in megahertz.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE(1)

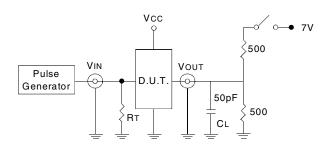
			FCT	Γ805	FCT	805A	
Symbol	Parameter	Conditions ⁽²⁾	Min.	Max.	Min.	Max.	Unit
tplh	Propagation Delay	CL = 50pF	1.5	5.6	1.5	5.3	ns
tphl	INA to OAn, INB to OBn	$RL = 500\Omega$					
tr.	Output Rise Time		_	1.5	_	1.5	ns
tF	Output Fall Time		_	1.5	_	1.5	ns
tsk(o)	Output skew: skew between outputs of all banks of		_	0.7	_	0.7	ns
	same package (inputs tied together)						
tsk(p)	Pulse skew: skew between opposite transitions		_	1	_	1	ns
	of same output (tphl tplh)						
tsk(PP)	Part-to-part skew: skew between outputs of different		_	1.5	_	1.5	ns
	packages at same power supply voltage,						
	temperature, package type and speed grade						
tpzl	Output Enable Time		1.5	8	1.5	8	ns
tpzh	OEA to OAn, OEB to OBn						
tPLZ	Output Disable Time		1.5	7	1.5	7	ns
tphz	OEA to OAn, OEB to OBn						

NOTES:

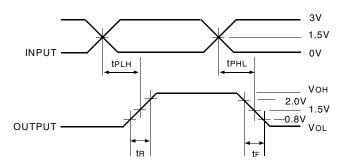
^{1.} Propagation delay range indicated by Min. and Max. limit is due to Vcc, operating temperature and process parameters. These propagation delay limits do not imply skew.

^{2.} See test circuits and waveforms.

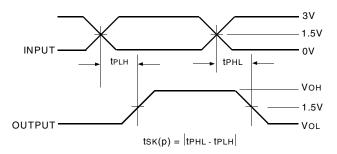
TEST CIRCUITS AND WAVEFORMS



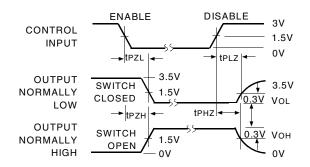
Test Circuits for All Outputs



Package Delay



Pulse Skew - tsk(P)



Enable and Disable Times

NOTES:

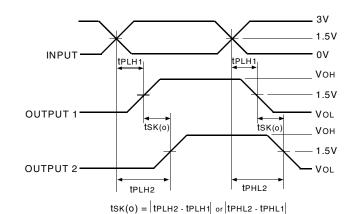
- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tr \leq 2.5ns; tr \leq 2.5ns

SWITCH POSITION

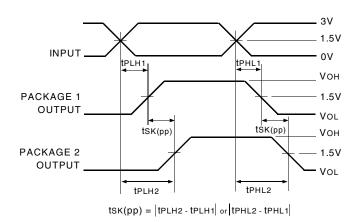
Test	Switch
Disable LOW Enable LOW	Closed
Disable HIGH Enable HIGH	GND

DEFINITIONS:

- CL = Load capacitance: includes jig and probe capacitance.
- RT = Termination resistance: should be equal to ZouT of the Pulse Generator.



Output Skew

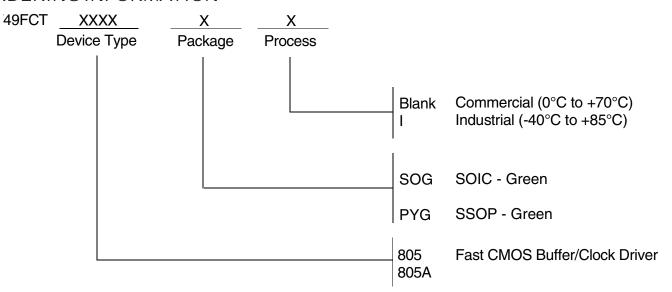


Part-to-Part Skew - tsk(PP)

NOTE:

1. Package 1 and Package 2 are same device type and speed grade.

ORDERING INFORMATION



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